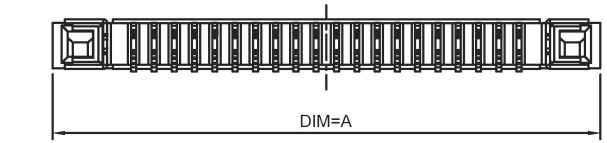
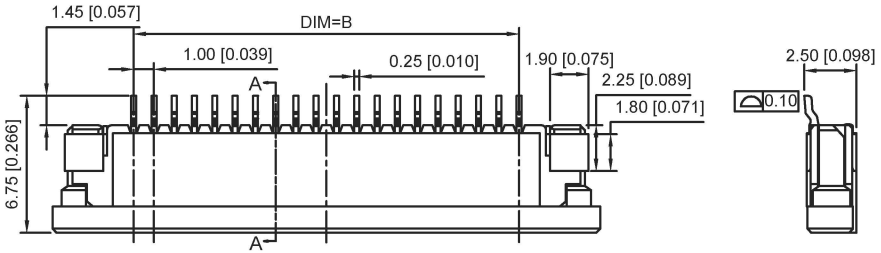
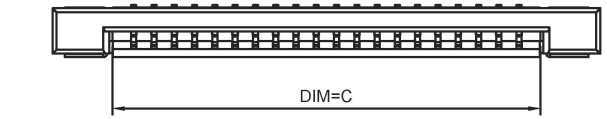






Pin	DIM A	DIM B	DIM C	
20	27.0	19.0	21.1	
19	26.0	18.0	20.1	
18	25.0	17.0	19.1	
17	24.0	16.0	18.1	
16	23.0	15.0	17.1	
15	22.0	14.0	16.1	
14	21.0	13.0	15.1	
13	20.0	12.0	14.1	
12	19.0	11.0	13.1	
11	18.0	10.0	12.1	
10	17.0	9.0	11.1	
09	16.0	8.0	10.1	
08	15.0	7.0	9.1	
07	14.0	6.0	8.1	
06	13.0	5.0	7.1	
05	12.0	4.0	6.1	
04	11.0	3.0	5.1	

Pin	DIM A	DIM B	DIM C	
40	47.0	39.0	41.1	
39	46.0	38.0	40.1	
38	45.0	37.0	39.1	
37	44.0	36.0	38.1	
36	43.0	35.0	37.1	
35	42.0	34.0	36.1	
34	41.0	33.0	35.1	
33	40.0	32.0	34.1	
32	39.0	31.0	33.1	
31	38.0	30.0	32.1	
30	37.0	29.0	31.1	
29	36.0	28.0	30.1	
28	35.0	27.0	29.1	
27	34.0	26.0	28.1	
26	33.0	25.0	27.1	
25	32.0	24.0	26.1	
24	31.0	23.0	25.1	
23	30.0	22.0	24.1	
22	29.0	21.0	23.1	
21	28.0	20.0	22.1	

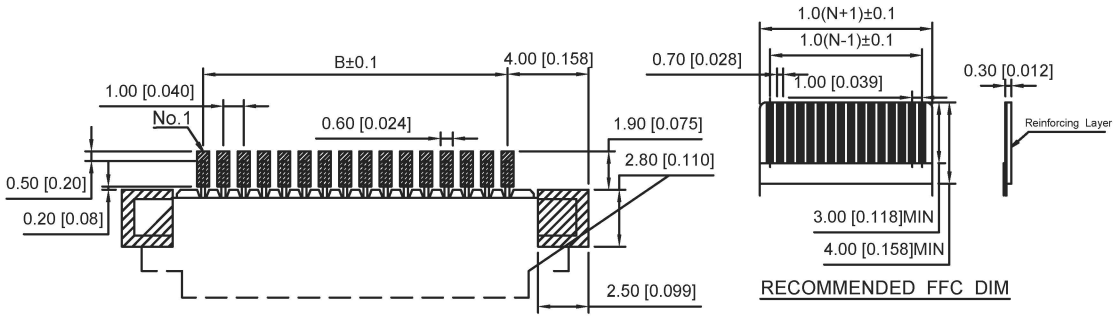
X10B25 U XX X
① ② ③ ④

① Series Name: X10B25=1.0 mm Pitch(H=2.5mm)

② Assembly style : L:Low Contact SMT Type U:Upper Contact SMT Type
D:Double-Face Contact SMT Type H:Back-flip Double-Face Contact SMT Type

③ Number of terminals :XX=04-40PIN

④ Plating : G:Gold Flash Over Nickel T:Tin Over Nickel



RECOMMENDED FFC DIM

RECOMMENDED PCB LAYOUT

3.PERFORMANCE
3.1: CURRENT RATING:O.5A/PIN
3.2: VOLTAGE RATING:50V (AC/DC)
3.3:CONTACT RESISTANCE:INITAL VALUE 30mOHM MAX.
3.4:INSULATON RESISTANCE:500MOHM in.
3.5:DIELECTRIC WITHSTANDING VOLTAGE:250V AC FOR 1MINUTE
3.6: DURABILITY: 20 TIMES Min.
3.7:QPERATING TEMPERATURE:-40□ +85□
OPERUTING HUMIDITY RANGE: 20% TO 85%

广东星坤科技股份有限公司
生效日期
文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED
ΔX				
ΔX				
ΔX				

REVISIONS

UNSPECIFIED TOLERANCES	
ANGLAR	±5°
L≤4	±0.2
4<L≤16	±0.3
16<L≤63	±0.4
L>63	±0.5

DSND		DATE		SCALE: N/A	MODEL TYPE: FPC CONNECTOR
DWN		DATE		VIEW:	PART NO.:
CHKD		DATE		UNIT: mm/in	
APPD		DATE		SIZE: A4	DWG NO.: X10B25UXXX

XKB INDUSTRIAL PRECISION CO.,LIMITED

WEIGHT	SHEET	REVISION
1.0g	1/1	A0

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